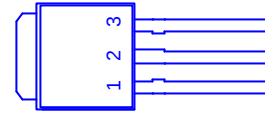
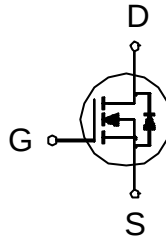


PRODUCT SUMMARY

$V_{(BR)DSS}$	$R_{DS(ON)}$	I_D
25	9.5mΩ	50A



1. GATE
2. DRAIN
3. SOURCE

ABSOLUTE MAXIMUM RATINGS ($T_C = 25\text{ }^{\circ}\text{C}$ Unless Otherwise Noted)

PARAMETERS/TEST CONDITIONS		SYMBOL	LIMITS	UNITS
Gate-Source Voltage		V_{GS}	± 20	V
Continuous Drain Current	$T_C = 25\text{ }^{\circ}\text{C}$	I_D	50	A
	$T_C = 100\text{ }^{\circ}\text{C}$		35	
Pulsed Drain Current ¹		I_{DM}	200	
Avalanche Current		I_{AR}	40	
Avalanche Energy	$L = 0.1\text{mH}$	E_{AS}	250	mJ
Repetitive Avalanche Energy ²	$L = 0.05\text{mH}$	E_{AR}	8.6	
Power Dissipation	$T_C = 25\text{ }^{\circ}\text{C}$	P_D	50	W
	$T_C = 100\text{ }^{\circ}\text{C}$		30	
Operating Junction & Storage Temperature Range		T_j, T_{stg}	-55 to 150	$^{\circ}\text{C}$
Lead Temperature (l_{16} " from case for 10 sec.)		T_L	275	

THERMAL RESISTANCE RATINGS

THERMAL RESISTANCE	SYMBOL	TYPICAL	MAXIMUM	UNITS
Junction-to-Case	$R_{\theta JC}$		2.5	$^{\circ}\text{C} / \text{W}$
Junction-to-Ambient	$R_{\theta JA}$		62.5	
Case-to-Heatsink	$R_{\theta CS}$	0.6		

¹Pulse width limited by maximum junction temperature.

²Duty cycle $\leq 1\%$

ELECTRICAL CHARACTERISTICS ($T_C = 25\text{ }^{\circ}\text{C}$, Unless Otherwise Noted)

PARAMETER	SYMBOL	TEST CONDITIONS	LIMITS			UNIT
			MIN	TYP	MAX	
STATIC						
Drain-Source Breakdown Voltage	$V_{(BR)DSS}$	$V_{GS} = 0V, I_D = 250\mu A$	25			V
Gate Threshold Voltage	$V_{GS(th)}$	$V_{DS} = V_{GS}, I_D = 250\mu A$	1	1.6	3	
Gate-Body Leakage	I_{GSS}	$V_{DS} = 0V, V_{GS} = \pm 20V$			± 250	nA
Zero Gate Voltage Drain Current	I_{DSS}	$V_{DS} = 20V, V_{GS} = 0V$			25	μA
		$V_{DS} = 20V, V_{GS} = 0V, T_C = 125\text{ }^{\circ}C$			250	

On-State Drain Current ¹	I _{D(ON)}	V _{DS} = 10V, V _{GS} = 10V	50			A
Drain-Source On-State Resistance ¹	R _{DS(ON)}	V _{GS} = 4.5V, I _D = 20A		11	16	mΩ
		V _{GS} = 10V, I _D = 25A		7.5	9.5	
Forward Transconductance ¹	g _{fs}	V _{DS} = 10V, I _D = 25A		32		S
DYNAMIC						
Input Capacitance	C _{iss}	V _{GS} = 0V, V _{DS} = 15V, f = 1MHz		1200	1800	pF
Output Capacitance	C _{oss}			600	1000	
Reverse Transfer Capacitance	C _{rss}			350	500	
Total Gate Charge ²	Q _g	V _{DS} = 10V, V _{GS} = 10V, I _D = 25A		25	50	nC
Gate-Source Charge ²	Q _{gs}			15		
Gate-Drain Charge ²	Q _{gd}			10		
Turn-On Delay Time ²	t _{d(on)}	V _{DS} = 15V, R _L = 1Ω I _D ≅ 50A, V _{GS} = 10V, R _{GEN} = 24Ω		6	16	nS
Rise Time ²	t _r			120	250	
Turn-Off Delay Time ²	t _{d(off)}			40	90	
Fall Time ²	t _f			105	200	
SOURCE-DRAIN DIODE RATINGS AND CHARACTERISTICS (T _c = 25 °C)						
Continuous Current	I _S				50	A
Pulsed Current ³	I _{SM}				150	
Forward Voltage ¹	V _{SD}	I _S = 25A, V _{GS} = 0V		0.9	1.3	V
Reverse Recovery Time	t _{rr}	I _F = I _S , dI _F /dt = 100A / μS		70		nS
Peak Reverse Recovery Current	I _{RM(REC)}			200		A
Reverse Recovery Charge	Q _{rr}			0.043		μC

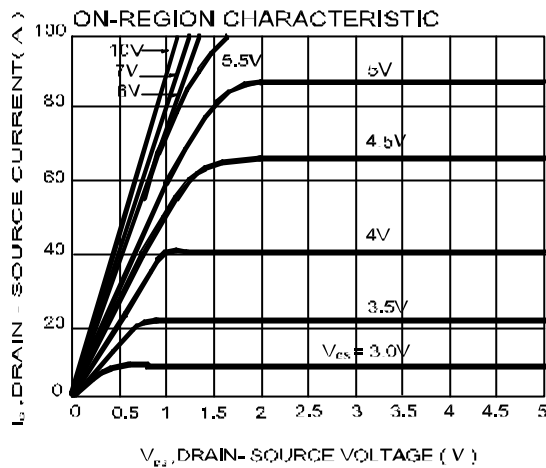
¹Pulse test : Pulse Width $\leq 300 \mu sec$, Duty Cycle $\leq 2\%$.

²Independent of operating temperature.

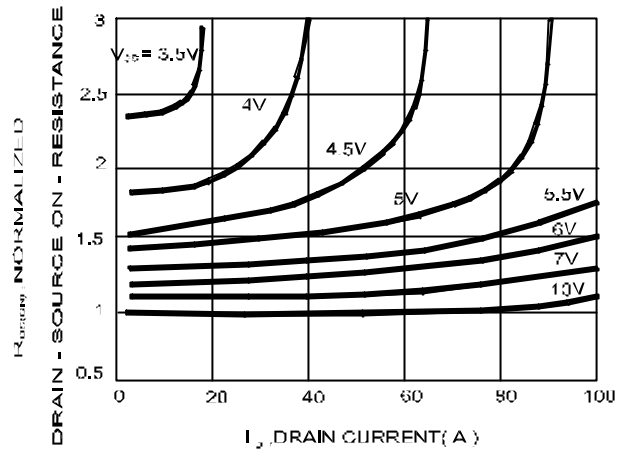
³Pulse width limited by maximum junction temperature.

REMARK: THE PRODUCT MARKED WITH "P0903BI", DATE CODE or LOT #

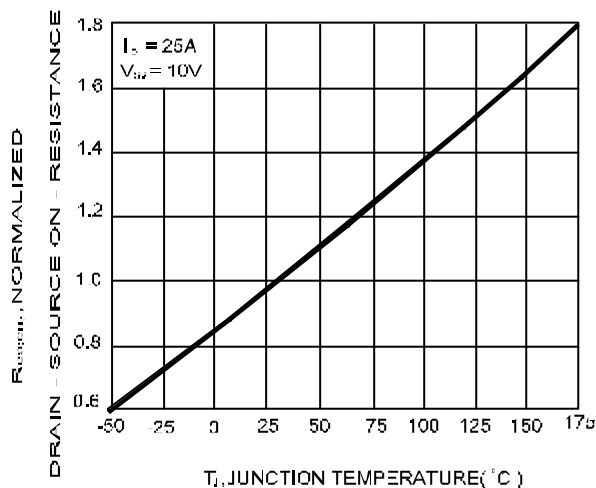
TYPICAL CHARACTERISTICS



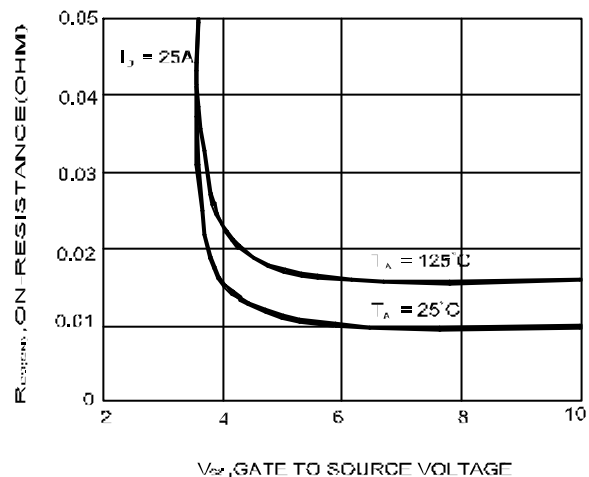
ON-RESISTANCE VARIATION WITH DRAIN CURRENT AND GATE



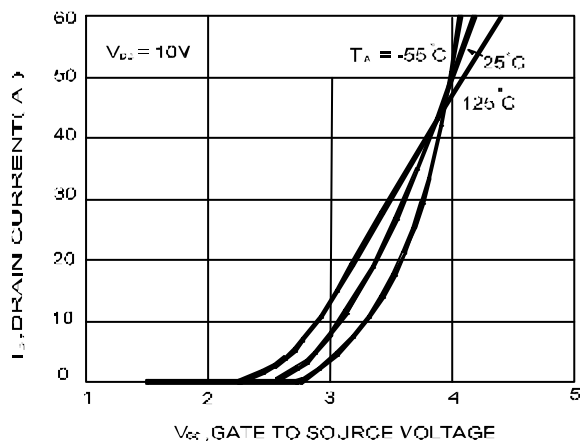
ON-RESISTANCE VARIATION WITH TEMPERATURE



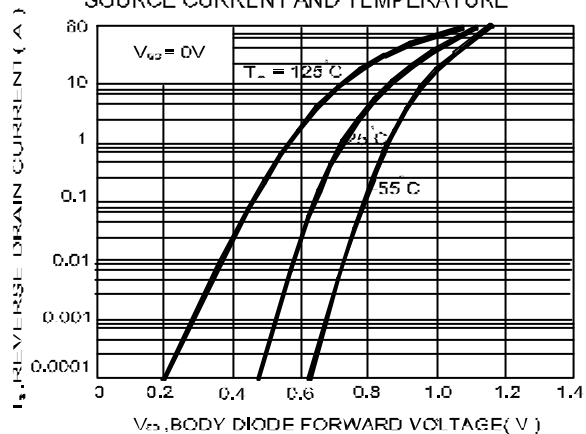
ON-RESISTANCE VARIATION WITH GATE-TO-SOURCE VOLTAGE

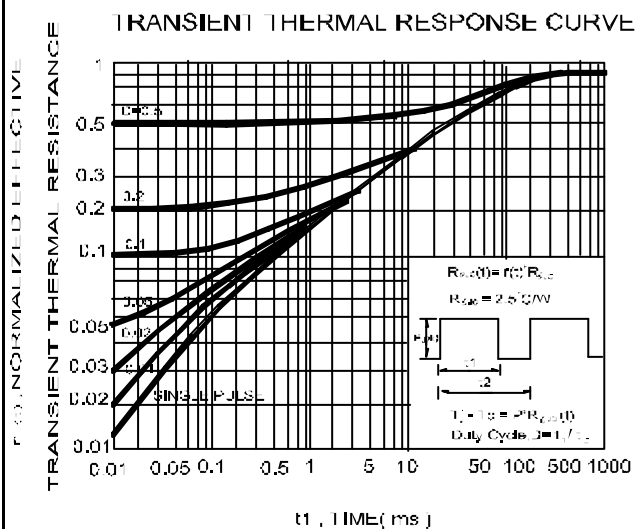
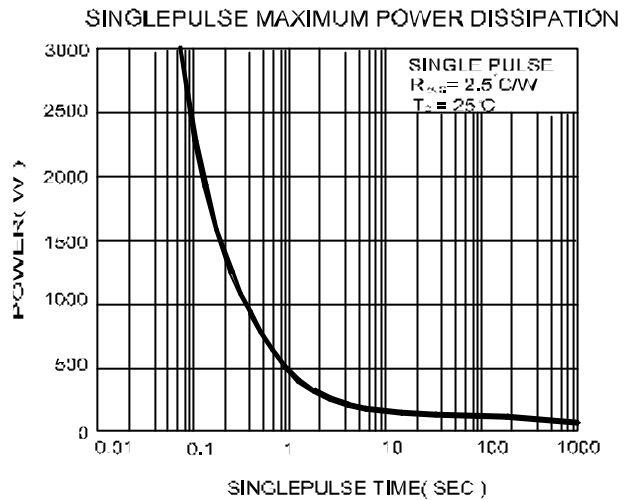
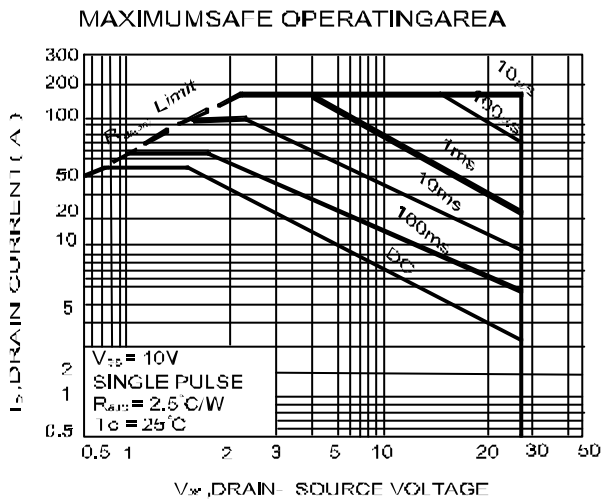
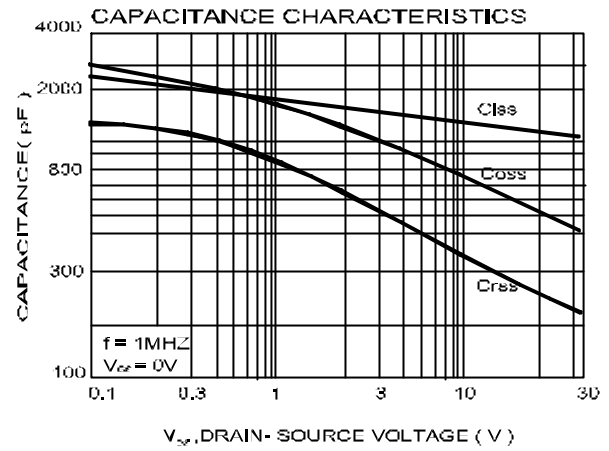
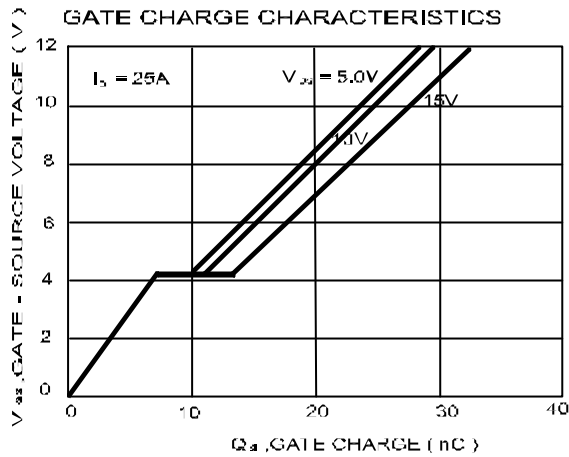


TRANSFER CHARACTERISTICS



BODY DIODE FORWARD VOLTAGE VARIATION WITH SOURCE CURRENT AND TEMPERATURE





TO-251 (IPAK) MECHANICAL DATA

Dimension	mm			Dimension	mm		
	Min.	Typ.	Max.		Min.	Typ.	Max.
A	13.7		15.3	H	1.4		2
B	2.2		2.4	I	6.4		6.8
C	0.4		0.6	J	5.2		5.5
D	0.4		0.6	K	0.6		0.9
E	0.9		1.5	L	0.4		0.8
F	7.0		8.0	M		2.3	
G	5.4		5.8	N			

